

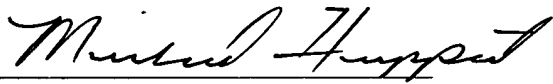
REMARKS

The present Preliminary Amendment is submitted to amend original claims 1, 4-6, 10-13 and 17-18. The amended claims are presented to delete the reference numerals therein.

Also, the abstract has been amended in order to remove the reference numerals therein. The changes to the abstract are submitted in the form of a substitute abstract. A copy of the abstract with changes marked therein is attached.

Respectfully submitted,

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ABSTRACT

A circuit board ~~(1)~~ includes a substrate ~~(2)~~ including electrode patterns ~~(22)~~ formed thereon, first chip components ~~(3a, 3b)~~ mounted on the substrate and a second chip component ~~(4)~~ mounted on a side of electrodes of the first chip components opposite from the substrate. The second chip component is bonded at one electrode ~~(41)~~ to an electrode ~~(31)~~ of the first chip component and is also bonded at the other electrode ~~(41)~~ to an electrode ~~(31)~~ of the first chip component. By stacking chip components in plural stages, it is possible to mount chip components with a high density on the substrate, thereby enabling reduction of the size of the circuit board.

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